ABSTRACT OF THE DISCLOSURE

Provided is a pressure-sensitive adhesive sheet for semiconductor processing having excellent followability to unevenness of an adherend having unevenness, and an excellent anchoring property. The pressure-sensitive adhesive sheet for semiconductor processing includes a pressure-sensitive adhesive layer formed of a UV-curable pressure-sensitive adhesive, and a base material. The UV-curable pressure-sensitive adhesive contains a base polymer, a photopolymerization initiator, and a phosphoric acid ester-based surfactant.

Fig. 1